

**In the Title:**

Please delete the title "Bonding Pad And Support Structure And Method For Their Fabrication" and insert in place thereof --Structure For Bonding Pad And Method For Its Fabrication--.

**In the Specification:**

After the title, please insert the sentence: --This is a continuation of application Serial No. 09/465,532 filed December 16, 1999.--

**In the Claims:**

Please cancel claims 1-32.

Please add the following new claims:

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--33. A composite structure comprising:  
a first metal pad structure comprising a first interconnect metal;  
a first via pad structure below said first metal pad structure, said first via pad structure comprising a plurality of segments of a first via metal and a first plurality of dielectric fillers, at least one of said plurality of segments of said first via metal contacting said first interconnect metal.--